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Quad Analog Switch/ Quad Multiplexer

The MC14016B quad bilateral switch is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. Each MC14016B consists of four independent switches capable of controlling either digital or analog signals. The quad bilateral switch is used in signal gating, chopper, modulator, demodulator and CMOS logic implementation.

Features

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Linearized Transfer Characteristics
- Low Noise 12 nV/ $\sqrt{\text{Cycle}}$, f \geq 1.0 kHz typical
- Pin-for-Pin Replacements for CD4016B, CD4066B (Note Improved Transfer Characteristic Design Causes More Parasitic Coupling Capacitance than CD4016)
- For Lower R_{ON}, Use The HC4016 High–Speed CMOS Device or The MC14066B
- This Device Has Inputs and Outputs Which Do Not Have ESD Protection. Antistatic Precautions Must Be Taken
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	V
l _{in}	Input Current (DC or Transient) per Control Pin	±10	mA
I _{SW}	Switch Through Current	±25	mA
P _D	Power Dissipation, per Package (Note 1)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: "D/DW" Packages: $-7.0 \text{ mW/}^{\circ}\text{C}$ From 65°C To 125°C This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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SOEIAJ-14 F SUFFIX CASE 965

MARKING DIAGRAMS



0010-14



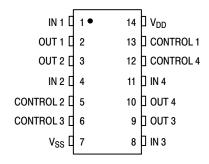
A = Assembly Location
WL. L = Wafer Lot

YY, Y = Year
WW, W = Work Week
G = Pb-Free Indicator

ORDERING INFORMATION

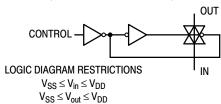
See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

PIN ASSIGNMENT

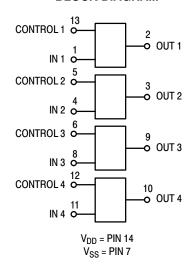


LOGIC DIAGRAM

(1/4 OF DEVICE SHOWN)



BLOCK DIAGRAM



Control	Switch
0 = V _{SS}	Off
1 = V _{DD}	On

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14016BDG	SOIC-14 (Pb-Free)	55 Units / Rail
MC14016BDR2G	SOIC-14 (Pb-Free)	2500 / Tape & Reel
NLV14016BDR2G*	SOIC-14 (Pb-Free)	2500 / Tape & Reel
MC14016BFELG	SOEIAJ-14 (Pb-Free)	2000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging

Specifications Brochure, BRD8011/D.
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

				-5	5°C		25°C		12	5°C	
Characteristic	Figure	Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Input Voltage Control Input	1	V _{IL}	5.0 10 15		- - -	- - -	1.5 1.5 1.5	0.9 0.9 0.9	- - -	- - -	Vdc
		V _{IH}	5.0 10 15	- - -	- - -	3.0 8.0 13	2.0 6.0 11	- - -	- - -	- - -	Vdc
Input Current Control	-	l _{in}	15	-	±0.1	-	±0.00001	±0.1	-	±1.0	μAdc
Input Capacitance Control Switch Input Switch Output Feed Through	-	C _{in}	- - - -	- - - -	- - - -	- - - -	5.0 5.0 5.0 0.2	- - - -	- - - -	- - - -	pF
Quiescent Current (Per Package) (Note 3)	2,3	I _{DD}	5.0 10 15	- - -	0.25 0.5 1.0	- - -	0.0005 0.0010 0.0015	0.25 0.5 1.0	- - -	7.5 15 30	μAdc
"ON" Resistance $(V_C = V_{DD}, R_L = 10 \text{ k}\Omega)$	4,5,6	R _{ON}									Ω
$(V_{in} = +10 \text{ Vdc})$ $(V_{in} = +0.25 \text{ Vdc}) \text{ V}_{SS} = 0 \text{ Vdc}$ $(V_{in} = +5.6 \text{ Vdc})$			10	- - -	600 600 600	- - -	260 310 310	660 660 660	- - -	840 840 840	
$(V_{in} = +15 \text{ Vdc})$ $(V_{in} = +0.25 \text{ Vdc}) \text{ V}_{SS} = 0 \text{ Vdc}$ $(V_{in} = +9.3 \text{ Vdc})$			15	- - -	360 360 360	- - -	260 260 300	400 400 400	- - -	520 520 520	
Δ "ON" Resistance Between any 2 circuits in a common package ($V_C = V_{DD}$) ($V_{in} = +5.0 \text{ Vdc}, V_{SS} = -5.0 \text{ Vdc}$) ($V_{in} = +7.5 \text{ Vdc}, V_{SS} = -7.5 \text{ Vdc}$)	-	ΔR _{ON}	5.0 7.5	- -			15 10			_ _ _	Ω
Input/Output Leakage Current (V _C = V _{SS})	-	_									μAdc
$(V_{in} = +7.5, V_{out} = -7.5 \text{ Vdc})$ $(V_{in} = -7.5, V_{out} = +7.5 \text{ Vdc})$			7.5 7.5	_ _	±0.1 ±0.1	- -	±0.0015 ±0.0015	±0.1 ±0.1	_ _	±1.0 ±1.0	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

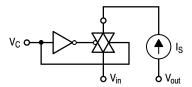
NOTE: All unused inputs must be returned to V_{DD} or V_{SS} as appropriate for the circuit application.

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 For voltage drops across the switch (\Delta V_{switch}) > 600 mV (> 300 mV at high temperature), excessive V_DD current may be drawn; i.e., the current out of the switch may contain both V_DD and switch input components. The reliability of the device will be unaffected unless the Maximum Ratings are exceeded. (See first page of this data sheet.) Reference Figure 14.

ELECTRICAL CHARACTERISTICS (Note 4) ($C_L = 50 \text{ pF}, T_A = 25^{\circ}C$)

Characteristic	Figure	Symbol	V _{DD} Vdc	Min	Typ (Note 5)	Max	Unit
Propagation Delay Time ($V_{SS} = 0 \text{ Vdc}$) V_{in} to V_{out} ($V_C = V_{DD}$, $R_L = 10 \text{ k}\Omega$)	7	t _{PLH} , t _{PHL}	5.0 10 15	- - -	15 7.0 6.0	45 20 15	ns
Control to Output $(V_{in} \leq 10 \text{ Vdc}, \text{ R}_L = 10 \text{ k}\Omega)$	8	t _{PHZ} , t _{PLZ} , t _{PZH} , t _{PZL}	5.0 10 15	- - -	34 20 15	120 110 100	ns
Crosstalk, Control to Output (V_{SS} = 0 Vdc) (V_{C} = V_{DD} , R_{in} = 10 k Ω , R_{out} = 10 k Ω , f = 1.0 kHz)	9	-	5.0 10 15	- - -	30 50 100	- - -	mV
Crosstalk between any two switches ($V_{SS} = 0 \text{ Vdc}$) $(R_L = 1.0 \text{ k}\Omega, f = 1.0 \text{ MHz},$ $\text{crosstalk} = 20 \log_{10} \frac{V_{out1}}{V_{out2}}$	_	-	5.0	-	- 80	-	dB
Noise Voltage (V _{SS} = 0 Vdc) (V _C = V _{DD} , f = 100 Hz)	10,11	-	5.0 10 15	- - -	24 25 30	- - -	nV/√Cycle
$(V_C = V_{DD}, f = 100 \text{ kHz})$			5.0 10 15	- - -	12 12 15	- - -	
$ \begin{array}{l} \text{Second Harmonic Distortion (V}_{SS} = -5.0 \text{ Vdc)} \\ \text{(V}_{in} = 1.77 \text{ Vdc, RMS Centered @ 0.0 Vdc,} \\ \text{R}_{L} = 10 \text{ k}\Omega, \text{ f} = 1.0 \text{ kHz)} \end{array} $	_	-	5.0	_	0.16	-	%
$\begin{split} &\text{Insertion Loss ($V_C = V_{DD}$, $V_{in} = 1.77$ Vdc,} \\ &V_{SS} = -5.0$ Vdc, RMS centered = 0.0$ Vdc, $f = 1.0$ MHz) \\ &I_{loss} = 20 log_{10} \frac{V_{out}}{V_{in}}) \\ &(R_L = 1.0 \text{ k}\Omega) \\ &(R_L = 10 \text{ k}\Omega) \\ &(R_L = 100 \text{ k}\Omega) \\ &(R_L = 1.0 \text{ M}\Omega) \end{split}$	12	_	5.0	- - - -	2.3 0.2 0.1 0.05	- - - -	dΒ
$\label{eq:bandwidth} \begin{split} &\text{Bandwidth } (-3.0 \text{ dB}) \\ &(\text{V}_{\text{C}} = \text{V}_{\text{DD}}, \text{V}_{\text{in}} = 1.77 \text{ Vdc}, \text{V}_{\text{SS}} = -5.0 \text{ Vdc}, \\ &\text{RMS centered @ 0.0 Vdc}) \\ &(\text{R}_{\text{L}} = 1.0 \text{ k}\Omega) \\ &(\text{R}_{\text{L}} = 10 \text{ k}\Omega) \\ &(\text{R}_{\text{L}} = 100 \text{ k}\Omega) \\ &(\text{R}_{\text{L}} = 1.0 \text{ M}\Omega) \end{split}$	12,13	BW	5.0	- - - -	54 40 38 37	- - - -	MHz
$\label{eq:continuity} \begin{array}{l} \text{OFF Channel Feedthrough Attenuation} \\ (V_{SS} = -5.0 \text{ Vdc}) \\ (V_{C} = V_{SS}, 20 \log_{10} \frac{V_{out}}{V_{in}} = -50 \text{dB}) \\ (R_{L} = 1.0 \text{k}\Omega) \\ (R_{L} = 10 \text{k}\Omega) \\ (R_{L} = 100 \text{k}\Omega) \\ (R_{L} = 1.0 \text{M}\Omega) \end{array}$	-	-	5.0	- - -	1250 140 18 2.0	- - - -	kHz

^{4.} The formulas given are for typical characteristics only at 25°C.
5. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



 V_{IL} : V_C is raised from V_{SS} until V_C = V_{IL} .

at $V_C = V_{IL}$: $I_S = \pm 10 \mu A$ with $V_{in} = V_{SS}$, $V_{out} = V_{DD}$ or $V_{in} = V_{DD}$, $V_{out} = V_{SS}$.

 V_{IH} : When V_C = V_{IH} to V_{DD} , the switch is ON and the R_{ON} specifications are met.

Figure 1. Input Voltage Test Circuit

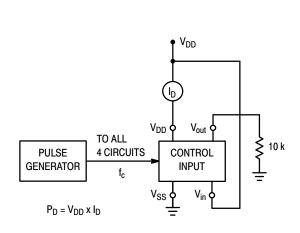


Figure 2. Quiescent Power Dissipation **Test Circuit**

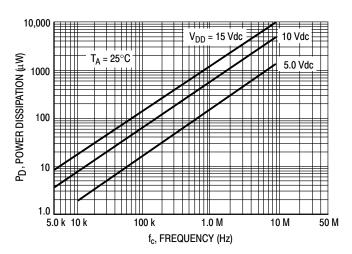


Figure 3. Typical Power Dissipation per Circuit (1/4 of device shown)

TYPICAL R_{ON} versus INPUT VOLTAGE

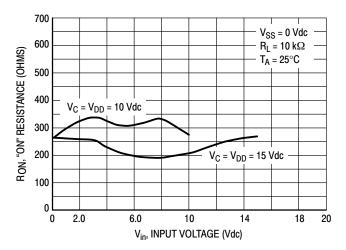


Figure 4. $V_{SS} = 0 V$

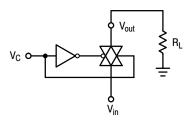


Figure 5. R_{ON} Characteristics Test Circuit

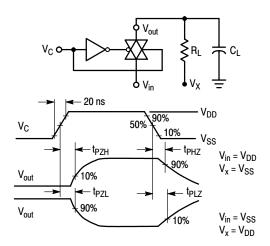


Figure 7. Turn-On Delay Time Test Circuit and Waveforms

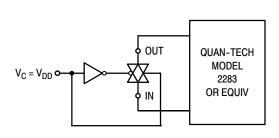


Figure 9. Noise Voltage Test Circuit

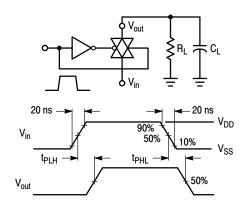


Figure 6. Propagation Delay Test Circuit and Waveforms

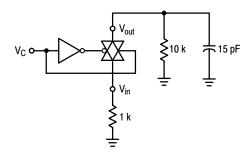


Figure 8. Crosstalk Test Circuit

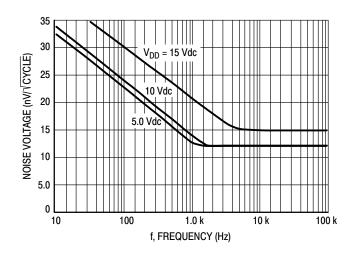


Figure 10. Typical Noise Characteristics

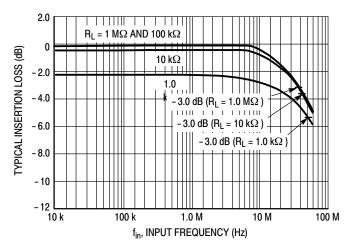


Figure 11. Typical Insertion Loss/Bandwidth Characteristics

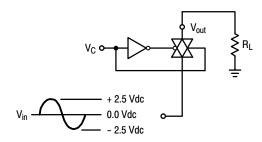


Figure 12. Frequency Response Test Circuit

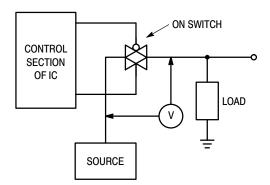


Figure 13. ΔV Across Switch

APPLICATIONS INFORMATION

Figure A illustrates use of the Analog Switch. The 0-to-5 V Digital Control signal is used to directly control a 5 V_{p-p} analog signal.

The digital control logic levels are determined by V_{DD} and V_{SS} . The V_{DD} voltage is the logic high voltage; the V_{SS} voltage is logic low. For the example, V_{DD} = +5 V logic high at the control inputs; V_{SS} = GND = 0 V logic low.

The maximum analog signal level is determined by V_{DD} and V_{SS} . The analog voltage must not swing higher than V_{DD} or lower than V_{SS} .

The example shows a 5 V_{p-p} signal which allows no margin at either peak. If voltage transients above V_{DD} and/or below V_{SS} are anticipated on the analog channels, external diodes (D_x) are recommended as shown in Figure B. These diodes should be small signal types able to absorb the maximum anticipated current surges during clipping.

The *absolute* maximum potential difference between V_{DD} and V_{SS} is 18.0 V. Most parameters are specified up to 15 V which is the *recommended* maximum difference between V_{DD} and V_{SS} .

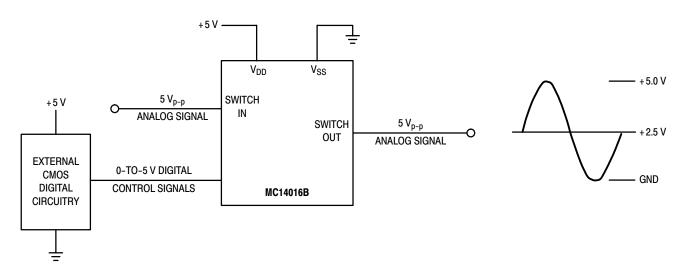


Figure A. Application Example

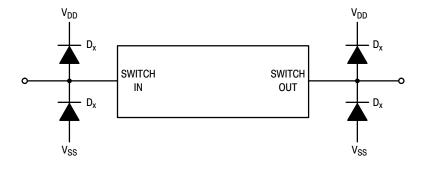
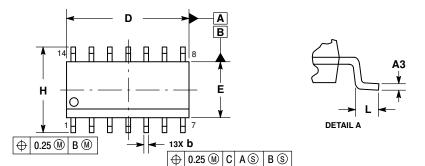
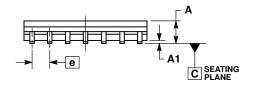


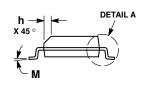
Figure B. External Germanium or Schottky Clipping Diodes

PACKAGE DIMENSIONS

SOIC-14 NB CASE 751A-03 ISSUE K







- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

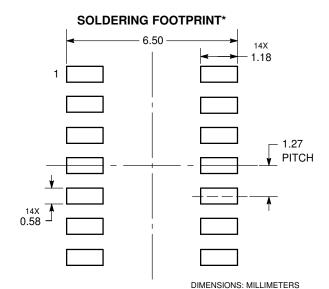
 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.

 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.

 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

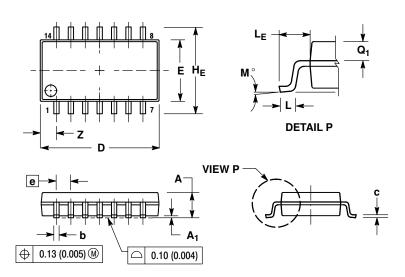
	MILLIN	IETERS	INCHES		
DIM	MIN MAX		MIN	MAX	
Α	1.35	1.75	0.054	0.068	
A 1	0.10	0.25	0.004	0.010	
А3	0.19	0.25	0.008	0.010	
b	0.35	0.49	0.014	0.019	
D	8.55	8.75	0.337	0.344	
Е	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050	BSC	
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.019	
L	0.40	1.25	0.016	0.049	
М	n۰	70	٥°	7°	



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOEIAJ-14 **CASE 965 ISSUE B**



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α		2.05		0.081	
A ₁	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
С	0.10	0.20	0.004	0.008	
D	9.90	10.50	0.390	0.413	
Е	5.10	5.45	0.201	0.215	
е	1.27	BSC	0.050 BSC		
HE	7.40	8.20	0.291	0.323	
L	0.50	0.85	0.020	0.033	
LE	1.10	1.50	0.043	0.059	
М	0 °	10 °	0 °	10°	
Q ₁	0.70	0.90	0.028	0.035	
Z		1.42		0.056	

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